PCN: V15-123-BASE-A

Product Change Notice

Issue Date: 26-Nov-2015

Change Type:

PCB Related Change: Change of Plating Process.

Parts Affected:

ALM-2812-TR1G
ALM-2812-BLKG

Description and Extent of Change:

Supplier is changing the thick Ni-Au Electroless Immersion process to the Electrolytic Ni-Au etch back process due to obsolescence of the Electroless Immersion process.

Reasons for Change:

To ensure continuous PCB supply.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The device specifications (electrical and mechanical) will remain the same to ensure Fit, Form, Function. Electrical characterization and reliability qualification is underway.

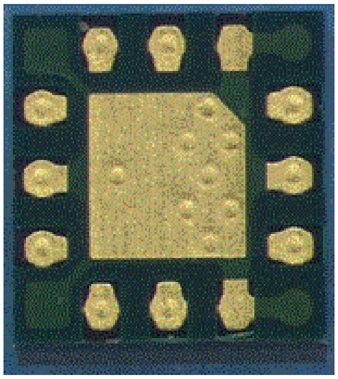
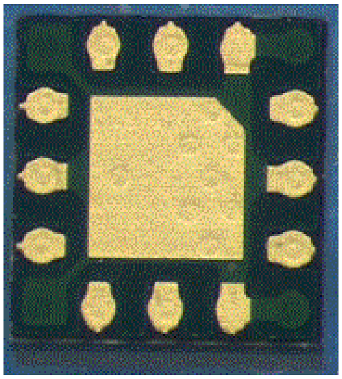
Effective Date of Change:

Product shipments using this change will begin Feb 2016, but initiation of the change may be spread over approximately 3 months. Timing of shipments will depend on completion of qualification, customer demand, and inventory levels.

Qualification Data:

Qualification will be completed by end of Jan'16

Appendix

	Current	New
Bottom View		

These changes have been reviewed and approved by Avago Technologies engineers and managers per Avago Technologies procedure: Change Control and Customer Notification, A-5962-6052-80.

Please contact your Avago Technologies field sales engineer or Contact Center (http://www.avagotech.com/contact/) for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.